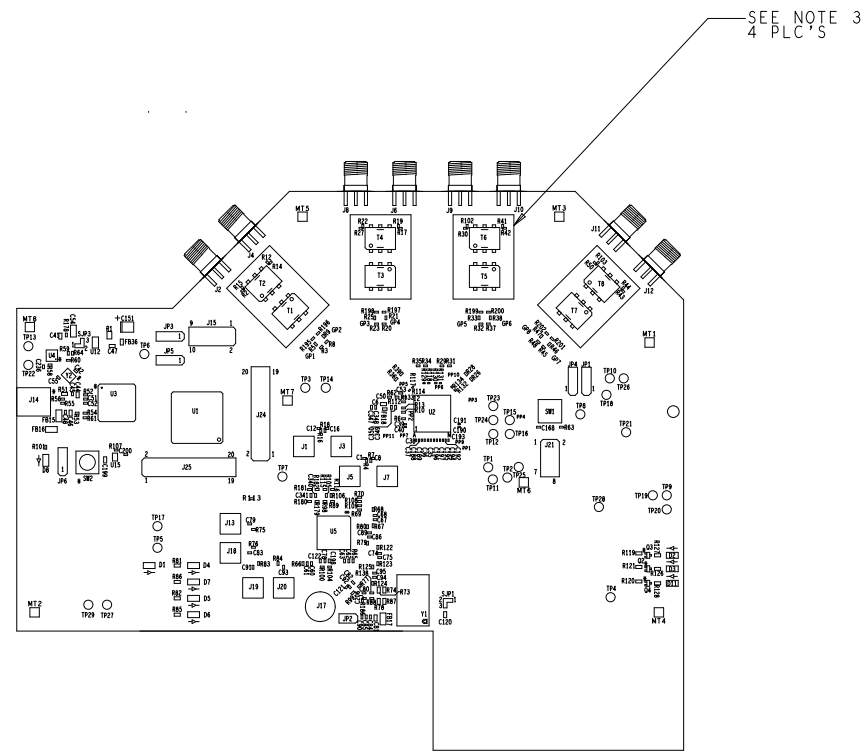


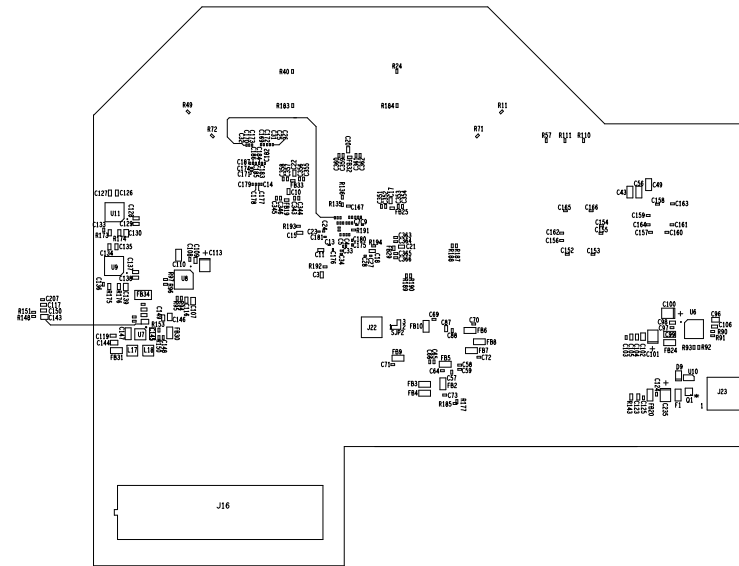
THIS DRAWING IS INTENDED TO HELP IN THE ASSEMBLY OF THE DESIGN.

| ZONE | | LTR | | REVISIONS | | DATE | APPROVED |
|------|--|-----|--|-------------|--|------|----------|
| | | | | DESCRIPTION | | | |
| | | | | | | | |

- REFER TO ODB++ FILE FOR SPECIFIC COMPONENT LOCATION INFORMATION.
- USE WATER SOLUBLE FLUX DURING BOARD ASSEMBLY.
RoHS COMPLIANT AND LEAD FREE.
- MOUNT THE RF FENCE ON THE TOP OF THE PCB AFTER BOARD ASSEMBLY.
SOLDER THE FENCE DOWN TO THE BOARD AROUND THE EDGES. NO GAPS.
PLACE THE RF COVER ON THE FENCE.



TOP VIEW



BOTTOM VIEW

| | | | | | | | | |
|--|----------------|-------------------|----------------------------------|-------|------|-----------|-------------|--------------|
| UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE: FRACTIONS DECIMALS ANGLES +/- .XX +/- .01 +/- .XXX +/- .005 +/- | CONTRACT NO. | | TEXAS INSTRUMENTS INC. | | | | | |
| | APPROVALS | DATE | ASSEMBLY DRAWING DAC3XJ8X EVM | | | | | |
| DRAWN JV SMITH | | 12-18-12 | | | | | | |
| MATERIAL | ENGR M GUIBORD | | 12-18-12 | SIZE | CODE | IDENT NO. | DRAWING NO. | REV. |
| SEE NOTE 5 | | | | B | | | | D |
| FINISH | | SEE NOTES 7, 8, 9 | | SCALE | | NONE | | SHEET 1 OF 1 |
| DO NOT SCALE DRAWING | | | | | | | | |

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